

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1260	438/5,6,14,15,106,125,460,462.ccls. and (substrate board wafer carrier) and (chip die ic) with align\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 08:22
L2	618	438/5,6,14,15,106,125,460,462.ccls. and (substrate board wafer carrier) and (chip die ic) with align\$4 and (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 08:24
L3	211	438/5,6,14,15,106,125,460,462.ccls. and (substrate board wafer carrier) and (chip die ic) with align\$4 same (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 08:53
L9	72	257/797 and (substrate board wafer carrier) and (chip die ic) with align\$4 same (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 08:54
L10	186	257/797 and (substrate board wafer carrier) and (chip die ic) with align\$4 and (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 08:56
L11	290	356/399,401,401.ccls. and (substrate board wafer carrier) and (chip die ic) with align\$4 and (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 09:06
L13	106	382/145,151.ccls. and (substrate board wafer carrier) and (chip die ic) with align\$4 and (align\$4 adj4 (device aparatus equipment)stage holder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/23 09:06